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Vishay Siliconix

Automotive P-Channel 12 V (D-S) 175 °C MOSFET

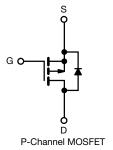
PowerPAK® SO-8L Order of the state of the s

PRODUCT SUMMARY				
V _{DS} (V)	-12			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.0040			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -2.5 \text{ V}$	0.0064			
I _D (A)	-238			
Configuration	Single			

FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SQJ123ELP (for detailed order number please see www.vishay.com/doc?79776)

ABSOLUTE MAXIMUM RATINGS (T_{C}	= 25 $^{\circ}$ C, unles	s otherwise noted	l)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V_{DS}	-12	V	
Gate-source voltage ^a		V _{GS}	± 8		
Continuous drain current	T _C = 25 °C b	1	-238		
Continuous drain current	T _C = 125 °C	I _D	-137		
Continuous source current (diode conduction) b		I _S	-340	А	
Pulsed drain current c		I _{DM}	400		
Single pulse avalanche current L = 0.1 mH		I _{AS}	73		
Single pulse avalanche energy		E _{AS}	270	mJ	
Maximum nawar dissination C	T _C = 25 °C	Р	375	W	
Maximum power dissipation ^c	T _C = 125 °C	P_{D}	125		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) d, e			260	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount f	R_{thJA}	44	°C/W
Junction-to-case (drain)		R_{thJC}	0.4	C/VV

Notes

- a. Not intended for continuous use with positive gate voltage > 5.0 V
- b. Package limited

S20-0922-Rev. B, 30-Nov-2020

- c. When mounted on 1" square PCB (FR4 material)
- d. See solder profile (www.vishay.com/doc?73257). For PowerPAK SO-8L, the end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- f. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %



Vishay Siliconix

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static	•				•		
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0, I _D = -250 μA		-12	-	-	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = -250 μA	-0.45	-0.6	-1.5	V
Gate-source leakage	I _{GSS}	V _{DS} =	0 V, V _{GS} = ± 8 V	-	-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = -12 V	-	-	-1	
Zero gate voltage drain current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = -12 V, T _J = 125 °C	-	-	-50	μΑ
		$V_{GS} = 0 V$	V _{DS} = -12 V, T _J = 175 °C	-	-	-150	
On-state drain current ^a	I _{D(on)}	$V_{GS} = -4.5 \text{ V}$	$V_{DS} \ge -5 V$	-30	-	-	Α
		$V_{GS} = -4.5 \text{ V}$	I _D = -10 A	-	0.0029	0.0040	
		V _{GS} = -4.5 V	I _D = -10 A, T _J = 125 °C	-	-	0.0057	
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = -4.5 V	I _D = -10 A, T _J = 175 °C	-	-	0.0066	Ω
		V _{GS} = -2.5 V	I _D = -10 A	-	0.0040	0.0064	
		V _{GS} = -1.8 V	I _D = -8 A	-	0.0070	0.0012	
Forward transconductance b	9 _{fs}	V _{DS} :	= -6 V, I _D = -20 A	-	82	-	S
Dynamic ^b							
Input capacitance	C _{iss}			-	8342	11 680	
Output capacitance	C _{oss}	$V_{GS} = 0 V$	$V_{DS} = -6 \text{ V}, f = 1 \text{ MHz}$	-	3173	4443	pF
Reverse transfer capacitance	C _{rss}			-	2844	3982	
Total gate charge ^c	Qg			-	120	180	
Gate-source charge ^c	Q _{gs}	$V_{GS} = -4.5 \text{ V}$	$V_{DS} = -6 \text{ V}, I_{D} = -15 \text{ A}$	-	15	-	nC
Gate-drain charge ^c	Q_{gd}			-	38	-	
Gate resistance	R_g		f = 1 MHz		2.2	3.3	Ω
Turn-on delay time ^c	t _{d(on)}			-	31	47	
Rise time ^c	t _r	$V_{DD} = -6 \text{ V, } R_L = 0.4 \Omega,$ $I_D \cong -15 \text{ A, } V_{GEN} = -4.5 \text{ V, } R_g = 1 \Omega$		-	53	80	ns
Turn-off delay time ^c	t _{d(off)}			-	181	272	
Fall time ^c	t _f			-	126	189	
Source-Drain Diode Ratings and Chara	acteristics b						
Pulsed current ^a	I _{SM}				-	-1360	Α
Forward voltage	V _{SD}	I _F = -10 A, V _{GS} = 0 V		-	-0.76	-1.2	V
Body diode reverse recovery time	t _{rr}			-	105	210	ns
Body diode reverse recovery charge	Q _{rr}	I_F = -10 A, di/dt = 100 A/μs, V_{DD} = 9 V, R_L = 10 Ω , L = 0.1 mH		-	172	346	nC
Reverse recovery fall time	t _a			-	51	-	
Reverse recovery rise time	t _b	7		-	56	-	ns
Body diode peak reverse recovery current	I _{RM(REC)}			-	-2.8	-	Α

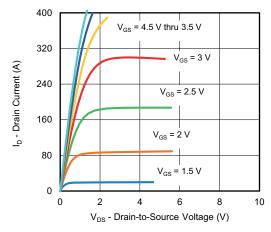
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

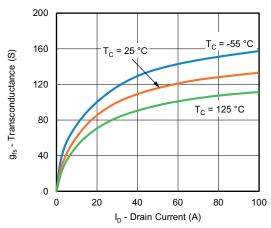
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



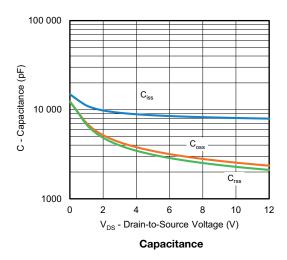
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

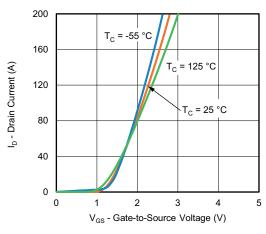


Output Characteristics

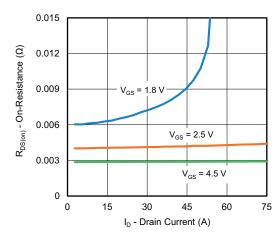


Transconductance

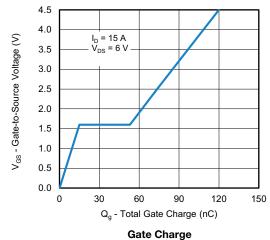




Transfer Characteristics

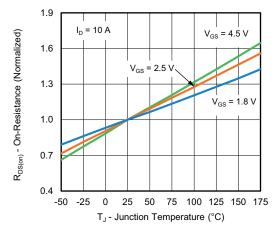


On-Resistance vs. Drain Current

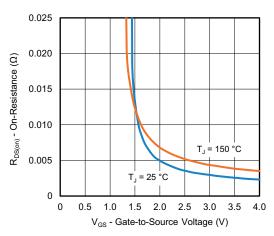




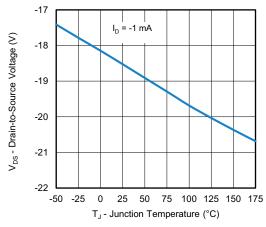
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



On-Resistance vs. Junction Temperature



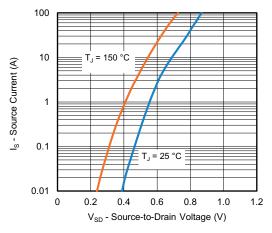
On-Resistance vs. Gate-to-Source Voltage



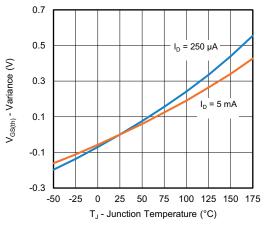
Drain-Source Breakdown vs. Junction Temperature

Note

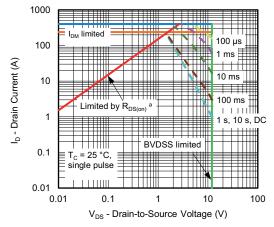
a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified



Source Drain Diode Forward Voltage



Threshold Voltage

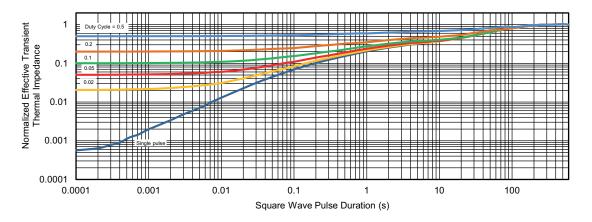


Safe Operating Area

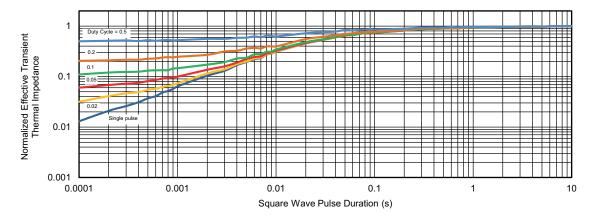
For technical questions, contact: automostechsupport@vishay



THERMAL RATINGS (T_C = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?79217.



PowerPAK® SO-8L (PPKSO8LWLA) Case Outline 3



DIM.		MILLIMETERS			INCHES			
DIIVI.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
Α	1.00	1.05	1.10	0.039	0.041	0.043		
A1	0.00		0.127	0.000		0.005		
b	0.33	0.41	0.49	0.013	0.016	0.019		
b1	0.43	0.51	0.59	0.017	0.020	0.023		
b2	4.00	4.10	4.20	0.157	0.161	0.165		
С	0.15	0.20	0.25	0.006	0.008	0.010		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.86	3.96	4.06	0.152	0.156	0.160		
D5	0.51	0.61	0.71	0.020	0.024	0.028		
D6	2.64	2.74	2.84	0.104	0.108	0.112		
е		1.27 BSC		0.050 BSC				
E	6.05	6.15	6.25	0.238	0.242	0.246		
E1	4.27	4.37	4.47	0.168	0.172	0.176		
E2	3.18	3.28	3.38	0.125	0.129	0.133		
E3	3.48	3.58	3.68	0.137	0.141	0.145		
E4	2.72	2.82	2.92	0.107	0.111	0.115		
E5	0.71	0.81	0.91	0.028	0.032	0.036		
L	0.62	0.72	0.82	0.024	0.028	0.032		
L1	0.92	1.07	1.22	0.036	0.042	0.048		
W1	0.31	0.41	0.51	0.012	0.016	0.020		
W4	0.31	0.36	0.41	0.012	0.014	0.016		
z1	0.37	0.47	0.57	0.015	0.019	0.022		
z2	0.99	1.09	1.19	0.039	0.043	0.047		
θ	0°		5°	0°		5°		

Note

• Millimeter will govern

Revison: 18-Sep-2023 1 Document Number: 76666



Recommended Land Pattern PowerPAK® SO-8L Single Short Ear



Dimensions in Millimeters (Inches)

Revision: 24-Aug-2021 1 Document Number: 78020



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